

INTRODUCE:

HVGT high voltage silicon rectifier assembly is made of high quality glass passivated chip and high reliability epoxy resin sealing structure, and through professional testing equipment inspection qualified after to customers.

FEATURES:

1. High reliability design.
2. High voltage design.
3. Power frequency ratio.
4. Conform to RoHS.
5. Epoxy resin molded in vacuumHave anticorrosion in the surface.

APPLICATIONS:

1. High frequency switching power supply.
2. Power supply of laser equipment .
3. General purpose high voltage rectifier.
4. Other.

MECHANICAL DATA:

1. Case: epoxy resin molding.
2. Terminal: welding axis.
3. Net weight: 950 grams (approx).

SHAPE DISPLAY:

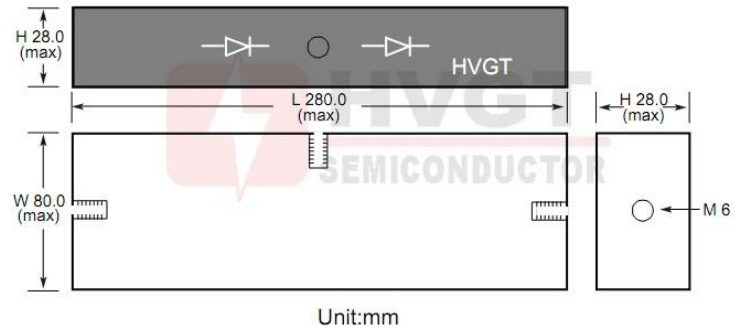


SIZE: (Unit:mm)

HVGT NAME: HVD-33

HVD-33 Series

Screw Holes M6



MAXIMUM RATINGS AND CHARACTERISTICS: (Absolute Maximum Ratings)

Items	Symbols	Condition	Data Value		Units
Repetitive Peak Reverse Voltage	V_{RRM}	$T_A=25^{\circ}C$	6.0	6.0	kV
Average Forward Current Maximum	I_{FAVM}	$T_A=40^{\circ}C$	10	10	A
Suege Current	I_{FSM}	$T_A=25^{\circ}C$; Half-Sine Wave; 8.3mS	200	200	A
Junction Temperature	T_J		125		$^{\circ}C$
Allowable Operation Case Temperature	T_C		-40~+125		$^{\circ}C$
Storage Temperature	T_{STG}		-40~+125		$^{\circ}C$

ELECTRICAL CHARACTERISTICS: $T_A=25^{\circ}C$ (Unless Otherwise Specified)

Items	Symbols	Condition	Data value		Units
Maximum Forward Voltage Drop	V_F	at $25^{\circ}C$; at $I_{F(AV)}$	11	11	V
Maximum Reverse Current	I_{R1}	at $25^{\circ}C$; at V_{RRM}	5.0	5.0	μA
	I_{R2}	at $100^{\circ}C$; at V_{RRM}	50	50	μA
Maximum Reverse Recovery Time	T_{RR}	at $25^{\circ}C$; $I_F=0.5I_R$; $I_R=I_{FAVM}$; $I_{RR}=0.25I_R$	100	100	nS
Junction Capacitance	C_J	at $25^{\circ}C$; $V_R=0V$; $f=1MHz$	--	--	pF



Fig 1

Forward Current Derating Curve

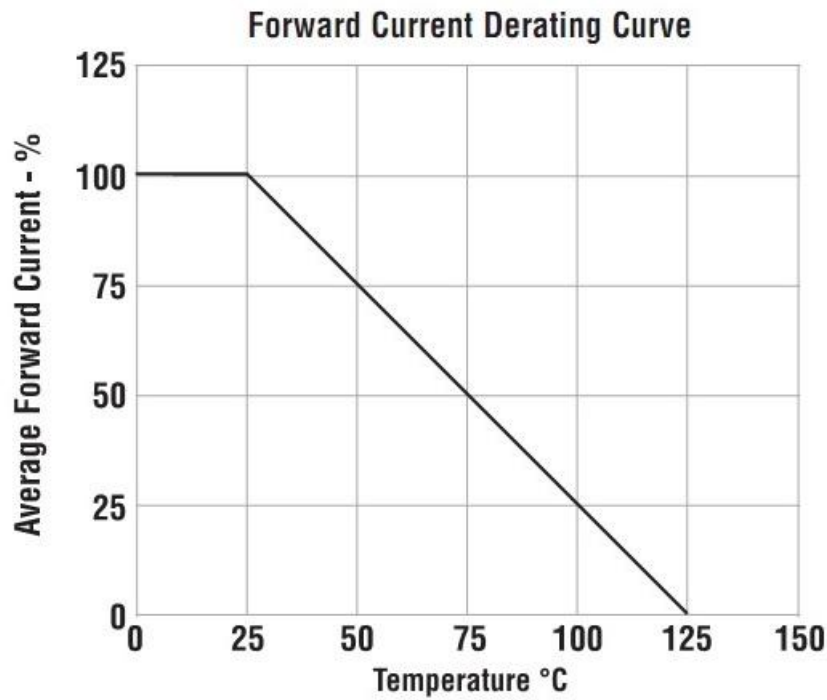


Fig 2

Non-Repetitive Surge Current

